

Appl. No.: 10/707,927
Amdt. Dated: 1/8/2006
Reply to Office action of: 10/28/2005

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended) A multiple-undercutting milling process for manufacturing a printed circuits board comprising a substrate and a metallic material conductive printed circuits adhered thereto, allowing subsequent bending of said printed circuit board up to 180° into a U-shape without deteriorating said printed circuits adhered to said printed circuit board substrate; said substrate having two opposite surfaces, a first surface for adhering conductive metallic material and a second surface suitable for milling:
~~constituted by comprising a process for preparing the said substrate of said printed circuit board (1) for the production of with bending areas (2) from whence to allowing bending such printed circuits board (1) characterized by consisting essentially of performing the simultaneously undercutting in multiple parallel strips on the said printed circuit's support board substrate second surface by means of a milling tool (3) allowing for subsequent bending of the printed circuit up to a value of 180° without deteriorating the metallic material conductive tracks adhered to the printed circuit substrate on the side opposite the milled surface.~~

Claim 2 (currently amended) A multiple-undercutting milling process for manufacturing a printed circuits board according to claim 1, characterized in that the said milling tool is a mill comprising comprises a roll provided with having multiple polishing strips or teeth on its surface.

Claim 3 (currently amended) A ~~printed circuit obtained~~ multiple-undercutting milling process for manufacturing a printed circuit board according to the process disclosed in claims 1 and 2, characterized in that the thickness of said conductive layer's thickness ranges between is from about 65 and to about 400 microns.

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Claim 4 (currently amended) A ~~printed circuit obtained~~ multiple-undercutting milling process for manufacturing a printed circuit board according to ~~the process disclosed in~~ claims 1 and 2, characterized in that the thickness of said conductive layer is 105 microns.

Claim 5 (currently amended) A ~~printed circuit obtained~~ multiple-undercutting milling process for manufacturing a printed circuit board according to ~~the process disclosed in~~ claims 1 and 2, characterized in that ~~the~~ said conductive layer's material ~~is~~ comprises copper.

Claim 6 (new) A multiple-undercutting milling process for manufacturing a printed circuit board according to claim 1, characterized in that said milling tool comprises a roll having multiple polishing teeth on its surface.